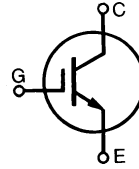


Low $V_{CE(sat)}$
High speed IGBT

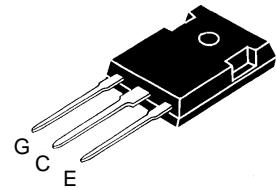
IXGH/IXGM 25 N100
IXGH/IXGM 25 N100A

| V_{CES} | I_{C25} | $V_{CE(sat)}$ |
|-----------|-----------|---------------|
| 1000 V | 50 A | 3.5 V |
| 1000 V | 50 A | 4.0 V |

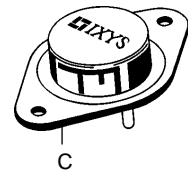


| Symbol | Test Conditions | Maximum Ratings | |
|-------------------------------|--|-----------------------------------|------------------|
| V_{CES} | $T_J = 25^\circ\text{C}$ to 150°C | 1000 | V |
| V_{CGR} | $T_J = 25^\circ\text{C}$ to 150°C ; $R_{GE} = 1\text{ M}\Omega$ | 1000 | V |
| V_{GES} | Continuous | ± 20 | V |
| V_{GEM} | Transient | ± 30 | V |
| I_{C25} | $T_C = 25^\circ\text{C}$ | 50 | A |
| I_{C90} | $T_C = 90^\circ\text{C}$ | 25 | A |
| I_{CM} | $T_C = 25^\circ\text{C}$, 1 ms | 100 | A |
| SSOA (RBSOA) | $V_{GE} = 15\text{ V}$, $T_{VJ} = 125^\circ\text{C}$, $R_G = 33\ \Omega$ Clamped inductive load, $L = 100\ \mu\text{H}$ | $I_{CM} = 50$ @ $0.8\ V_{CES}$ | A |
| P_c | $T_C = 25^\circ\text{C}$ | 200 | W |
| T_J | | -55 ... +150 | $^\circ\text{C}$ |
| T_{JM} | | 150 | $^\circ\text{C}$ |
| T_{stg} | | -55 ... +150 | $^\circ\text{C}$ |
| M_d | Mounting torque (M3) | 1.13/10 | Nm/lb.in. |
| Weight | | TO-204 = 18 g, TO-247 = 6 g | |
| | Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s | 300 | $^\circ\text{C}$ |

TO-247 AD (IXGH)



TO-204 AE (IXGM)



G = Gate, C = Collector,
E = Emitter, TAB = Collector

Features

- International standard packages
- 2nd generation HDMOS™ process
- Low $V_{CE(sat)}$
 - for low on-state conduction losses
- High current handling capability
- MOS Gate turn-on
 - drive simplicity
- Voltage rating guaranteed at high temperature (125°C)

Applications

- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switch-mode and resonant-mode power supplies

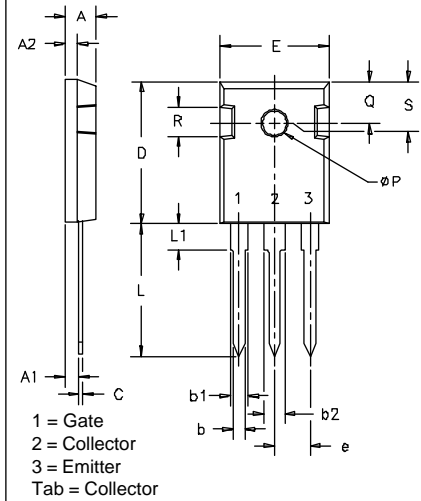
Advantages

- Easy to mount with 1 screw (TO-247) (isolated mounting screw hole)
- High power density

| Symbol | Test Conditions | Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified) | | |
|---------------|---|---|------|--|
| | | min. | typ. | max. |
| BV_{CES} | $I_C = 3\text{ mA}$, $V_{GE} = 0\text{ V}$ | 1000 | | V |
| $V_{GE(th)}$ | $I_C = 250\ \mu\text{A}$, $V_{CE} = V_{GE}$ | 2.5 | | 5 V |
| I_{CES} | $V_{CE} = 0.8 \cdot V_{CES}$ $V_{GE} = 0\text{ V}$ | | | $T_J = 25^\circ\text{C}$: 250 μA $T_J = 125^\circ\text{C}$: 1 mA |
| I_{GES} | $V_{CE} = 0\text{ V}$, $V_{GE} = \pm 20\text{ V}$ | | | $\pm 100\text{ nA}$ |
| $V_{CE(sat)}$ | $I_C = I_{C90}$, $V_{GE} = 15\text{ V}$ | | | 25N100: 3.5 V 25N100A: 4.0 V |

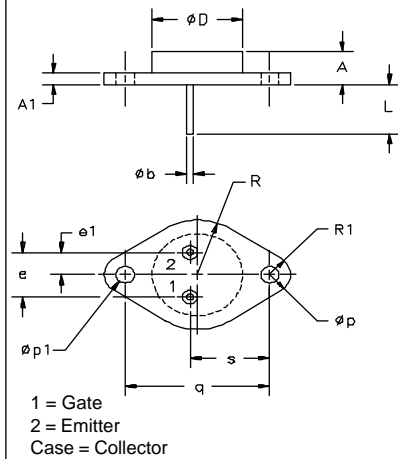
| Symbol | Test Conditions | Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified) | | |
|--------------|--|---|------|----------|
| | | min. | typ. | max. |
| g_{fs} | $I_C = I_{C90}$; $V_{CE} = 10\text{ V}$, Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$ | 8 | 15 | S |
| C_{ies} | $V_{CE} = 25\text{ V}$, $V_{GE} = 0\text{ V}$, $f = 1\text{ MHz}$ | | 2750 | pF |
| C_{oes} | | | 200 | pF |
| C_{res} | | | 50 | pF |
| Q_g | $I_C = I_{C90}$, $V_{GE} = 15\text{ V}$, $V_{CE} = 0.5 V_{CES}$ | | 130 | 180 nC |
| Q_{ge} | | | 25 | 60 nC |
| Q_{gc} | | | 55 | 90 nC |
| $t_{d(on)}$ | Inductive load, $T_J = 25^\circ\text{C}$ $I_C = I_{C90}$, $V_{GE} = 15\text{ V}$, $L = 300\ \mu\text{H}$, $V_{CE} = 0.8 V_{CES}$, $R_G = R_{off} = 33\ \Omega$ Remarks: Switching times may increase for $V_{CE}(\text{Clamp}) > 0.8 \cdot V_{CES}$, higher T_J or increased R_G | | 100 | ns |
| t_{ri} | | | 200 | ns |
| $t_{d(off)}$ | | | 500 | ns |
| t_{fi} | | 25N100A | 500 | ns |
| E_{off} | | 25N100A | 5 | mJ |
| $t_{d(on)}$ | Inductive load, $T_J = 125^\circ\text{C}$ $I_C = I_{C90}$, $V_{GE} = 15\text{ V}$, $L = 300\ \mu\text{H}$, $V_{CE} = 0.8 V_{CES}$, $R_G = R_{off} = 33\ \Omega$ Remarks: Switching times may increase for $V_{CE}(\text{Clamp}) > 0.8 \cdot V_{CES}$, higher T_J or increased R_G | | 100 | ns |
| t_{ri} | | | 250 | ns |
| E_{on} | | | 3.5 | mJ |
| $t_{d(off)}$ | | 25N100 | 720 | 1000 ns |
| t_{fi} | | 25N100A | 950 | 3000 ns |
| E_{off} | 25N100 | 10 | mJ | |
| E_{off} | 25N100A | 8 | mJ | |
| R_{thJC} | | | | 0.62 K/W |
| R_{thCK} | | 0.25 | | K/W |

TO-247 AD Outline



| SYM | INCHES | | MILLIMETERS | |
|----------|----------|----------|-------------|----------|
| | MIN | MAX | MIN | MAX |
| A | .185 | .209 | 4.7 | 5.3 |
| A1 | .087 | .102 | 2.2 | 2.54 |
| A2 | .059 | .098 | 2.2 | 2.6 |
| b | .040 | .055 | 1.0 | 1.4 |
| b1 | .065 | .084 | 1.65 | 2.13 |
| b2 | .113 | .123 | 2.87 | 3.12 |
| C | .016 | .031 | .4 | .8 |
| D | .819 | .845 | 20.80 | 21.46 |
| E | .610 | .640 | 15.75 | 16.26 |
| e | .215 BSC | | 5.45 BSC | |
| L | .780 | .800 | 19.81 | 20.32 |
| L1 | | .177 | | 4.50 |
| ϕP | .140 | .144 | 3.55 | 3.65 |
| Q | .212 | .244 | 5.4 | 6.2 |
| R | .170 | .216 | 4.32 | 5.49 |
| S | | .242 BSC | | 6.15 BSC |

TO-204AE Outline



| SYM | INCHES | | MILLIMETERS | |
|-----------|-----------|------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | .250 | .450 | 6.4 | 11.4 |
| A1 | .060 | .135 | 1.53 | 3.42 |
| ϕb | .057 | .063 | 1.45 | 1.60 |
| ϕD | | .875 | | 22.22 |
| e | .420 | .440 | 10.67 | 11.17 |
| e1 | .205 | .225 | 5.21 | 5.71 |
| L | .440 | .480 | 11.18 | 12.19 |
| ϕp | .151 | .165 | 3.84 | 4.19 |
| $\phi p1$ | .151 | .165 | 3.84 | 4.19 |
| q | 1.187 BSC | | 30.15 BSC | |
| R | .495 | .525 | 12.58 | 13.33 |
| R1 | .131 | .188 | 3.33 | 4.77 |
| s | .655 | .675 | 16.64 | 17.14 |

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETS and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715
4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025

Fig. 1 Saturation Characteristics

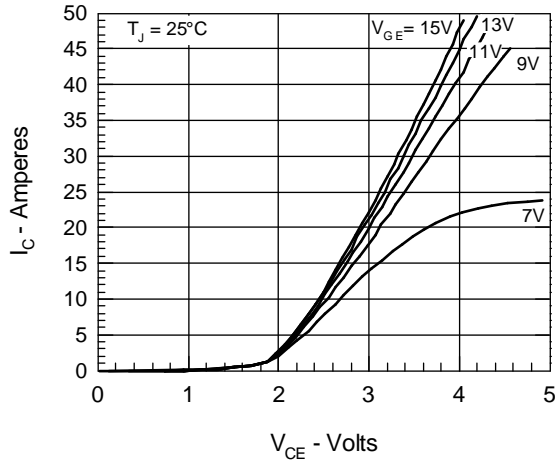


Fig. 2 Output Characteristics

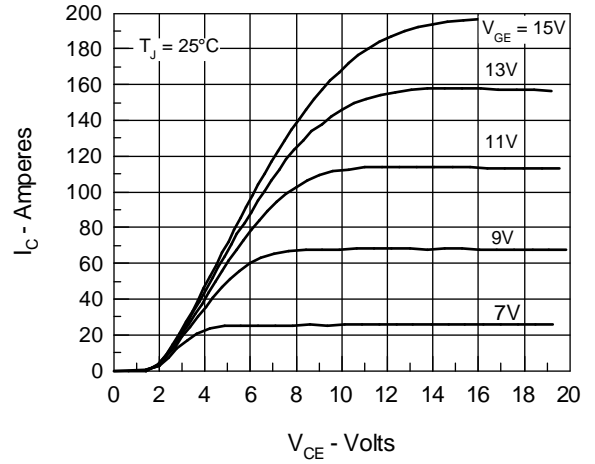


Fig. 3 Collector-Emitter Voltage vs. Gate-Emitter Voltage

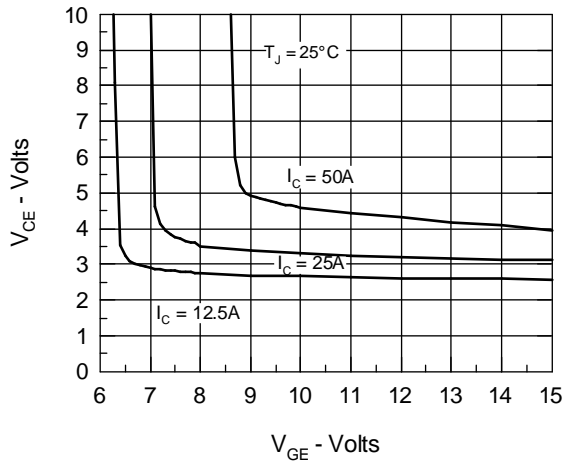


Fig. 4 Temperature Dependence of Output Saturation Voltage

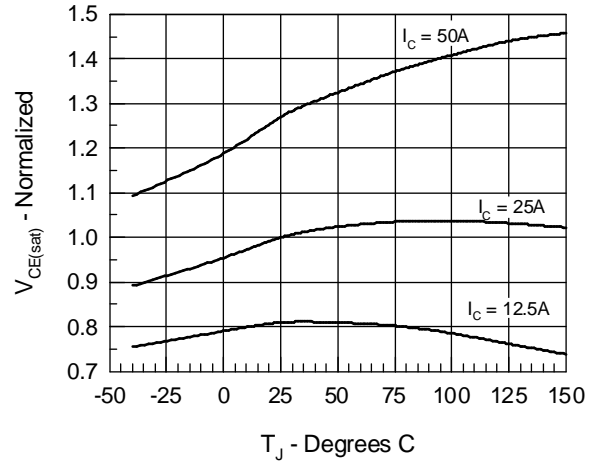


Fig. 5 Input Admittance

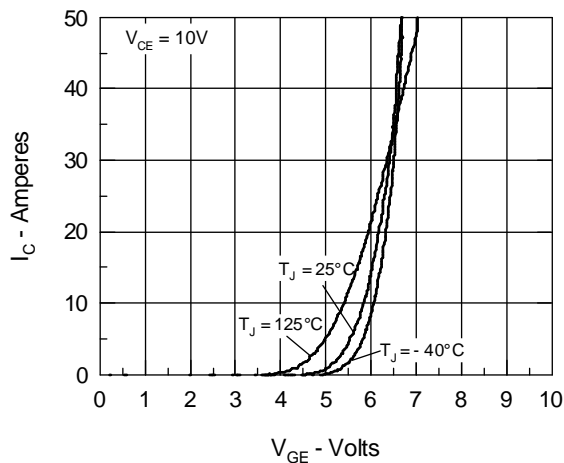


Fig. 6 Temperature Dependence of Breakdown and Threshold Voltage

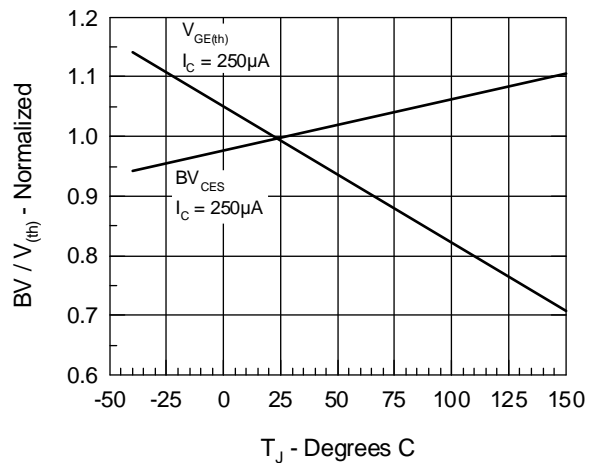


Fig.7 Gate Charge

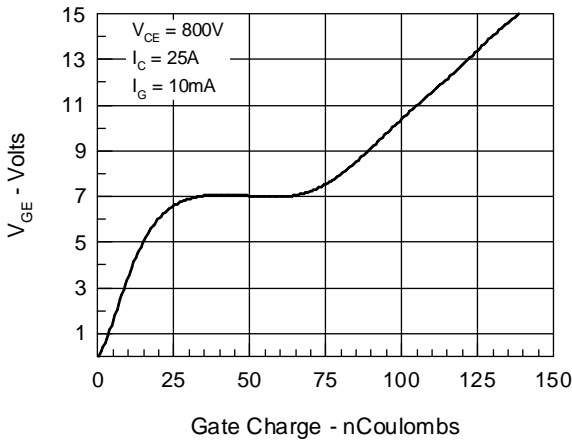


Fig.8 Turn-Off Safe Operating Area

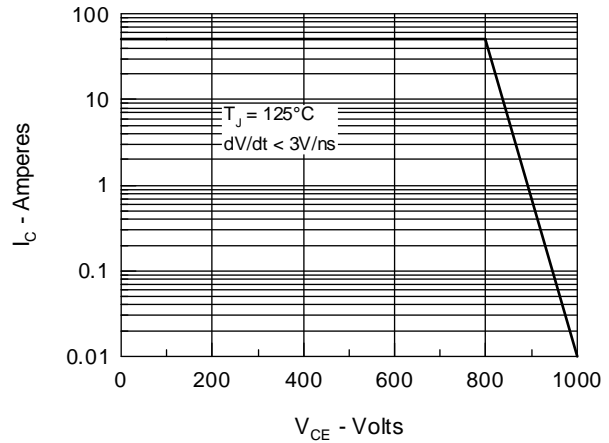


Fig.9 Capacitance Curves

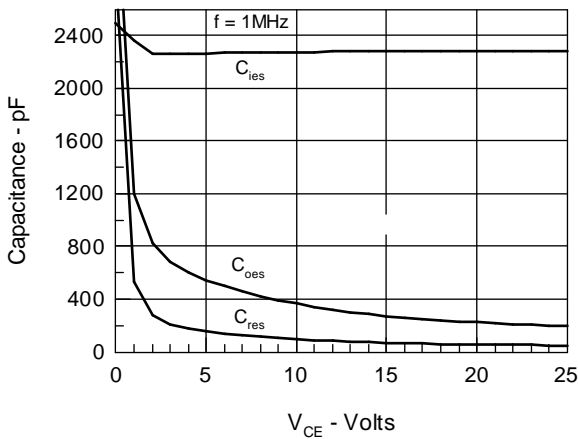
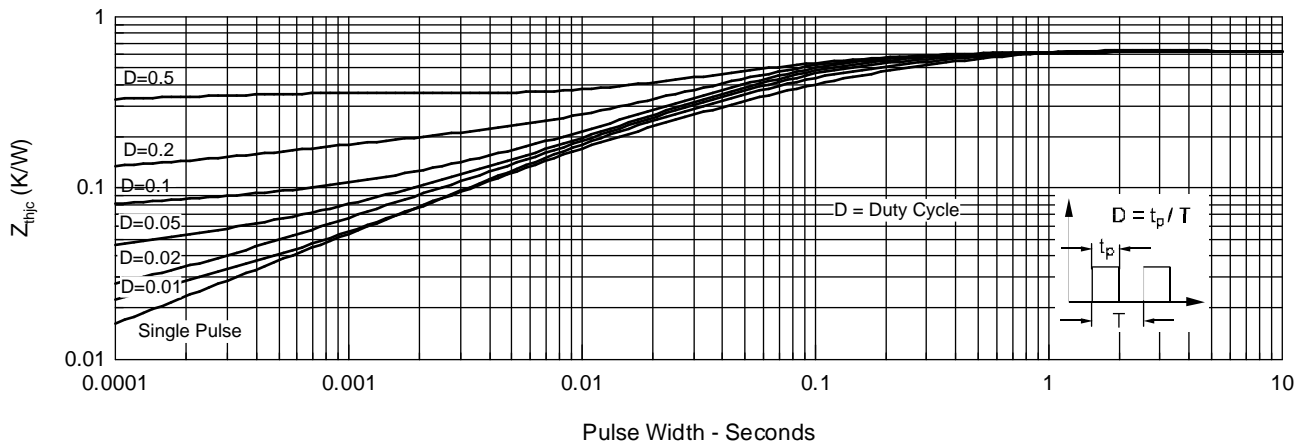


Fig.10 Transient Thermal Impedance



IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETS and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715
4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025



Стандарт Электрон Связь

Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию .

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России , а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

Минимальные сроки поставки, гибкие цены, неограниченный ассортимент и индивидуальный подход к клиентам являются основой для выстраивания долгосрочного и эффективного сотрудничества с предприятиями радиоэлектронной промышленности, предприятиями ВПК и научно-исследовательскими институтами России.

С нами вы становитесь еще успешнее!

Наши контакты:

Телефон: +7 812 627 14 35

Электронная почта: sales@st-electron.ru

Адрес: 198099, Санкт-Петербург,
Промышленная ул, дом № 19, литера Н,
помещение 100-Н Офис 331